#### **MICROWAVE POWER GaAs FET**

#### **High Power GaAs FETs (L, S-Band)**

#### **Features**

- High power
  - $P_{1dB}$  = 39.5 dBm at 2.6 GHz
- High gain
- G<sub>1dB</sub> = 8.5 dB at 2.6 GHz
  Hermetically sealed package

#### RF Performance Specifications ( $T_a = 25^{\circ} C$ )

| Characteristics                          | Symbol           | Condition                            | Unit | Min. | Тур. | Max |
|------------------------------------------|------------------|--------------------------------------|------|------|------|-----|
| Output Power at 1dB<br>Compression Point | P <sub>1dB</sub> |                                      | dBm  | 38.5 | 39.5 | _   |
| Power Gain at 1dB<br>Compression Point   | G <sub>1dB</sub> | V <sub>DS</sub> = 10V<br>f = 2.6 GHz | dB   | 7.5  | 8.5  | _   |
| Drain Current                            | I <sub>DS</sub>  |                                      | А    | _    | 2.0  | 2.5 |
| Power Added Efficiency                   | N <sub>add</sub> |                                      | %    | _    | 38   | _   |
| Channel-Temperature Rise                 | $\Delta T_{ch}$  | NOTE 1                               | °C   | _    | _    | 80  |

#### Electrical Characteristics (T<sub>a</sub> = 25° C)

| Characteristic                   | Symbol                | Condition                                     | Unit | Min. | Тур. | Max  |
|----------------------------------|-----------------------|-----------------------------------------------|------|------|------|------|
| Trans-conductance                | gm                    | V <sub>DS</sub> =3V<br>I <sub>DS</sub> =1.8 A | mS   | _    | 1600 | _    |
| Pinch-off Voltage                | $V_{GSoff}$           | V <sub>DS</sub> =3V<br>I <sub>DS</sub> =350mA | V    | -1.0 | -3.0 | -4.0 |
| Saturated Drain Current          | I <sub>DSS</sub>      | V <sub>DS</sub> =3V<br>V <sub>GS</sub> =0V    | А    | _    | 5.0  | 6.5  |
| Gate to Source Breakdown Voltage | $V_{GSO}$             | I <sub>GS</sub> =-105 μA                      | V    | -5   | _    | _    |
| Thermal Resistance               | R <sub>th (c-c)</sub> | Channel to case                               | °C/W | _    | 3.8  | 4.8  |

NOTE 1: $\Delta$ Tch = ( $V_{DS} \times I_{DS} + Pin - P_{1dB}$ ) x  $R_{th(c-c)}$ 

The information contained here is subject to change without notice.

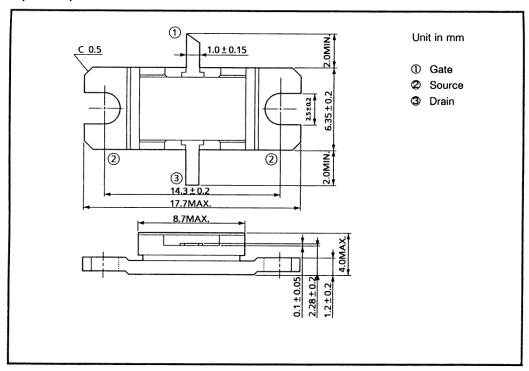
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# Absolute Maximum Ratings ( $T_a = 25^{\circ} C$ )

| Characteristic                      | Symbol           | Unit | Rating  |
|-------------------------------------|------------------|------|---------|
| Drain Source Voltage                | V <sub>DS</sub>  | V    | 15      |
| Gate Source Voltage                 | V <sub>GS</sub>  | V    | -5      |
| Drain Current                       | I <sub>D</sub>   | А    | 6.5     |
| Total Power Dissipation (Tc = 25°C) | P <sub>T</sub>   | W    | 30      |
| Channel Temperature                 | T <sub>ch</sub>  | °C   | 175     |
| Storage Temperature                 | T <sub>stg</sub> | °C   | -65~175 |

#### Package Outline (2-9D2A)



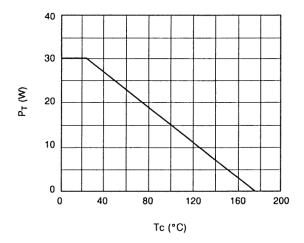
### **Handling Precautions for Packaged Type**

Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.

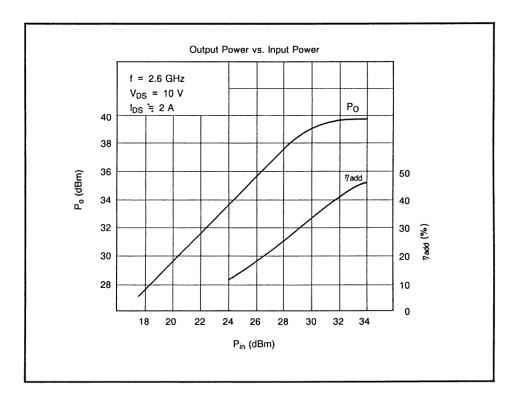
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#### Power Dissipation vs. Case Temperature



#### **RF Performances**

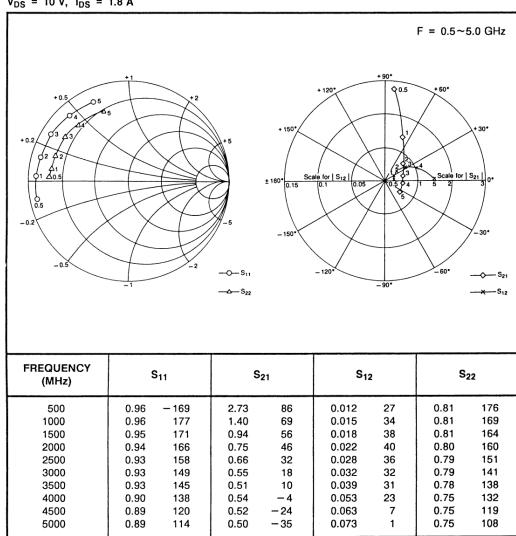


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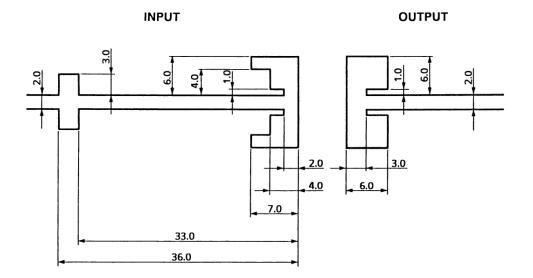
### TNM2600-7 S-Parameters (MAGN. and ANGLES)

 $V_{DS}$  = 10 V,  $I_{DS}$  = 1.8 A



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## Drawing of Matching Network for TNM2600-7



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